

ELECTROCONDUCTIVES

DOTITE FC-415

1. Product Introduction

DOTITE FC-415 is a carbon paste designed for use in membrane switches and flexible circuitry. It can be used to protect circuitry formed with silver conductive paste, and has excellent printability, excellent adhesion to silver paste cured films, and excellent blocking resistance properties.

2. Specifications

	FC-415	Remarks
Recommended Curing Conditions	150°C, 20 mins.	
Viscosity	180±40 d Pa·s	DSTM-203 (Viscotester VT-04, No. 2 rotor, at 23°C)
Volume Resistivity	2.0 × 10 ⁻¹ Ω · cm or lower	DSTM-101
Surface Resistivity	200 Ω · □	At 10μm film thickness
Adhesion	100/100	DSTM-401 (PET 100μm)
Pencil Hardness	F or higher	DSTM-302
Appearance	Black Paste	DSTM-351

3. Instructions and Warnings

- Store at 10°C or below. Reseal and return to refrigerated storage after use.
- When removing this material from refrigerated storage, the paste may become contaminated when opened if condensation has formed on the paste or container. Allow it to sit for one hour to ensure it reaches room temperature (23°C) before opening the container.
- Stir the material thoroughly from the bottom of the container until uniform before use. Properties may be negatively affected if not mixed properly.
- If dilution is required, use DOTITE P Thinner.
- This product contains organic solvent and is flammable. Take necessary precautions and follow recommended procedures when handling this product.
- For other handling and safety information, please refer to the SDS documentation for this product.

The above data are derived from tests conducted by Fujikura Kasei under lab conditions and do not represent this product's properties in all environments. We recommend that the curing conditions, cured film properties, safety precautions, overall applicability for the user's intended purpose, and other factors be confirmed on-site before use.